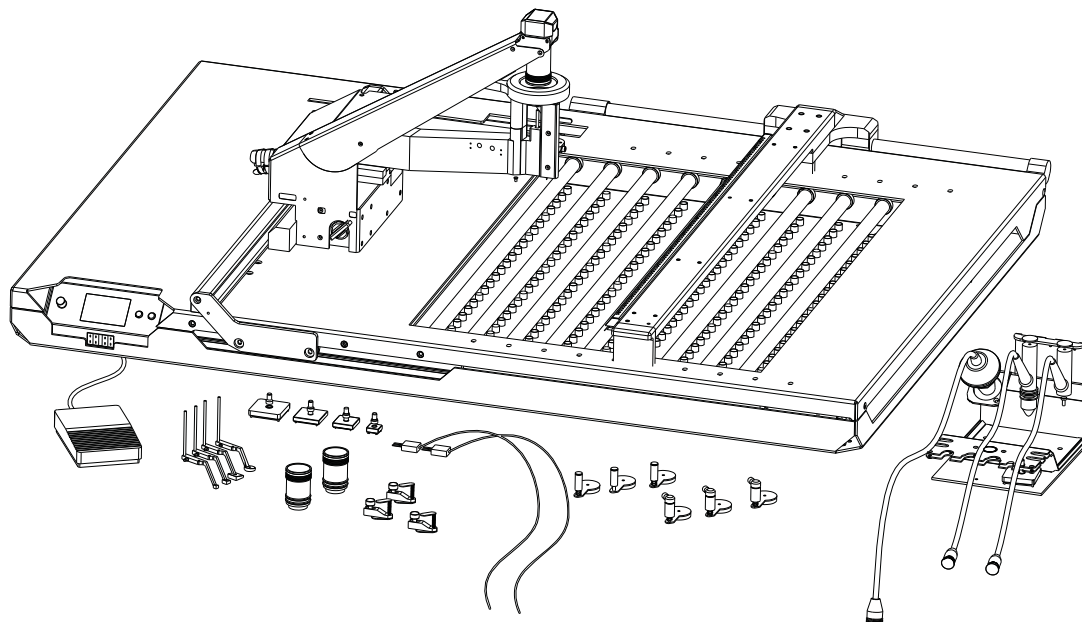


**EXPERT 10.6-HXXV**


Rework Station with 10000W hybrid under heater. The heating area of 500x650mm<sup>2</sup> is adjustable to PCB size. Automated SMD placement process by Auto-Vision-Placer (AVP) incl. Easy-Solder software package and DBL 06 control unit with six high resolution sensors inputs for thermocouples (Type K).

This system is particularly suitable for large size PCBs like server boards, telecommunication or batch PCBs with mid-size to very big components.

**Standard Equipment (Art.No DB00.1071)**





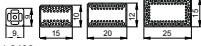



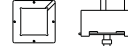


- Tool set for dispensing, placing, residual solder removal and soldering with magazine
- Set of placement nozzles XL-type (BGA/CSP) 5mm, 8mm, 15mm with O-Ring
- Set of solder nozzles (BGA) 15mm, 27mm, 35mm, 40mm
- Two camera lenses (BGA und CSP)
- Two thermo couple sensors (Type K)
- Six PCB magnet holders 40.5mm (3xstandard and 3xEasy-Lock)
- Three PCB clips to install at hand rest
- Foot switch
- Rework ABC and manual

**Technical Data**

System power consumption:	10500 VA	
Power solder pen:	300 W, 35 l/min	
Power underheater:	5000 - 10000 W, 9 x IR-lamps	
Effective heating area:	500 x 650 mm <sup>2</sup>	
PCB size recommended:	530 x 710 mm <sup>2</sup>	
Resolution motion system:	0.001 mm	
Placement accuracy	± 0.030 mm	(CSP)
	± 0.040 mm	(BGA)
	± 0.070 mm	(Maxi BGA)*
High resolution CMOS-camera:	5 Mio. Pixel, USB2	
Camera field of view (FOV):	32 x 42 mm <sup>2</sup>	(CSP)
	42 x 57 mm <sup>2</sup>	(BGA)
	71 x 96 mm <sup>2</sup>	(Maxi BGA)*
Mains:	3 Phases, 400VAC, Fuse 16A, Type C Connector Type CEE 32A (3 phase)	
Pressurized air:	5 - 8 bar, 100 l/min Clean dry air	
Foot print:	13000 x 900 mm <sup>2</sup>	
*Optional extras		

## EXPERT 10.6-HXXV

### Optional Extras

DVSX.0007	Report with pcb identification for ES 05, licence RP	 Report
SF66.0110	Lens Maxi BGA for AVP4/4XL, f=16mm, 65*85mm	 Maxi-BGA AVP4
LW40.1097	Soldering nozzle set CSP/QFN (lead free)* for all CSP types, 4 pieces (9, 11, 13, 16)	 (length + 1.4 mm)
LW40.1099	Solder nozzle set BGA 7^ for all (98%) types of BGA, 7 pieces	
LW01.0400	Soldering tool set SO (lead free)* for all SO...SOL...TSOP, 4 pieces	 (length + 1.4 mm)
LW01.0100	Soldering tool set QFP for all PLCC ...QFP, 7 pieces	
SF36.1005	PCB flex support 40.5 HIF 10, "18 pin"	
SF03.0014	PCB magnet holder Easy Lock 40.5 (snap) for IR/IRD/IRH/IRF/HIF	 40.5
LWxx.xxx4	Reballing oven and mask for all types of BGA/CSP, your choice	
SF71.0001	Side Camera for ES 05, camera, stand, cable, DVD	
DB00.0025	Nitrogen input for DBL 04/05/06 (2.p.r) reduces consumption of N2 for vacuum	 N
SF00.0028	Line connector CEE 32 A for HIF-08/09/10/IRF07 with hints	